

REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1 R	Initial Registration	S.H.KIM		2024.09.23.

A

A

B

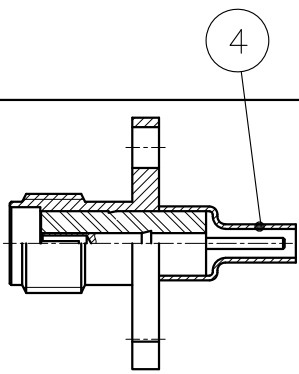
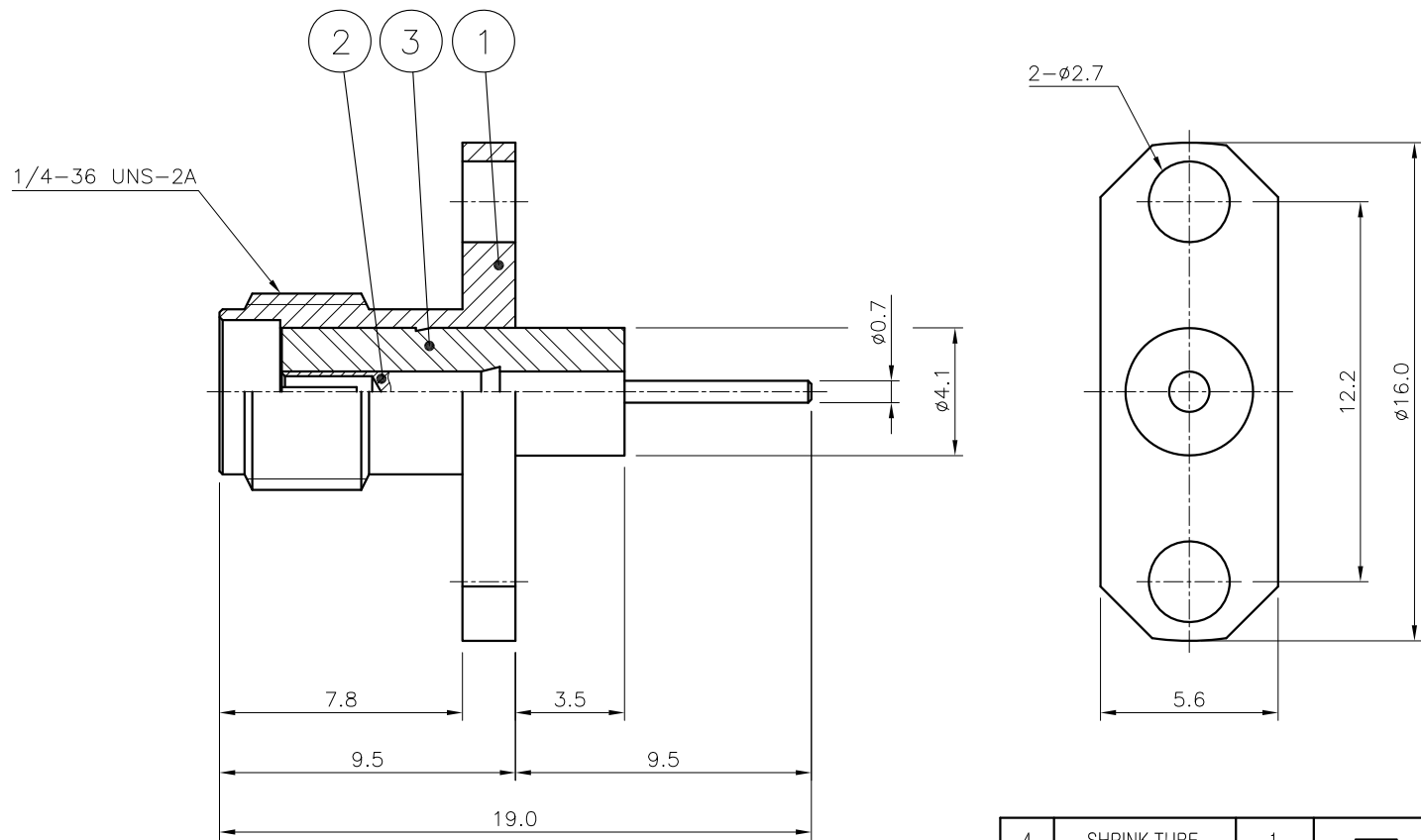
B

C

C

D

D



SCALE 2/1

주 기

1. 완제품 조립 후 Ø4.0-10mm SHRINK TUBE를
절연체 위로 수축하여 핀 보호

4	SHRINK TUBE	1	—	—	ATU00358-N/1
3	INSULATOR	1	TEFLON		DIN00110-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT04420-5/2
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00347-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 09. 23.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY			
MATERIAL —	CHECKED BY			TITLE SMA50 SOLDER END JS-2H	
	DRAWN BY S.H.KIM				
FINISH —	SCALE 4/1	UNIT mm		A4	DWG NO. CN01554-7/3
					REVISION I R